CLAIMS

1. An epoxy resin composition, comprising:

an epoxy resin;

a curing agent comprising a triphenylmethane-type phenol resin;

alumina particles at a content of 50% by volume or more with respect to a total amount of the epoxy resin composition; and

a silane compound which does not have a functional group that is reactive with an epoxy group and which has a functional group that is unreactive with an epoxy group, wherein the silane compound has a structure in which the functional group that is unreactive with an epoxy group is bound to a silicon atom, or is bound to a silicon atom via a chain hydrocarbon group having 1 to 5 carbon atoms, and in which the functional group that is unreactive with an epoxy group comprises a (meth)acryloyloxy group,

wherein the epoxy resin composition is a solid composition for sealing an element of an electronic component by low-pressure transfer molding, injection molding or compression molding.

2. The epoxy resin composition according to claim 1, wherein a content of the silane compound is from 0.01% by mass to 20% by mass with respect to a total amount of the epoxy resin.

3. The epoxy resin composition according to any one of claims 1 to 2, wherein the silane compound comprises 3-methacryloxypropyltrimethoxysilane.

4. The epoxy resin composition according to any one of claims 1 to 3, further comprising silica particles.

5. An electronic component device, having an element sealed with the epoxy resin composition according to any one of claims 1 to 4.